

Technology Landscape, Trends and Opportunities in the Global Semiconductor and IC Packaging Material Market

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Abstracts

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The technologies in semiconductor and IC packaging materials has undergone significant change in recent years, with traditional dual in line packaging t%li%advanced integrated circuit packaging. The rising wave of new technologies such as grid array (GA) is creating significant potential for semiconductor and IC packaging materials in consumer electronics, aerospace and defense, and communications and telecom applications t%li%protect and insulate electronic components from external threats.

In semiconductor and IC packaging material market, various technologies such as SOP (Small Outline Package), GA (Grid Array), QFP (Quad Flat Package), and DIP(Dual In-Line Package) technologies are used in the consumer electronics, aerospace and defense, medical devices, communications and telecom, automotive industry, and energy and lighting applications. Increasing demand for consumer electronics and increasing R&D by key players towards making the electronic packaging materials are creating new opportunities for various semiconductor and IC packaging material technologies.

This report analyzes technology maturity, degree of disruption, competitive intensity, market potential, and other parameters of various technologies in the semiconductor and IC packaging material market. Some insights are depicted below by a sample figure. For more details on figures, the companies researched, and other objectives/benefits on this research report, please download the report brochure.

The study includes technology readiness, competitive intensity, regulatory compliance,



disruption potential, trends, forecasts and strategic implications for the global semiconductor and IC packaging material technology by application, technology, and region as follows:

Technology Readiness by Technology Type

Competitive Intensity and Regulatory Compliance

Disruption Potential by Technology Type

Trends and Forecasts by Technology Type [\$M shipment analysis from 2018 t%li%2030]:

SOP (Small Outline Package)

GA (Grid Array)

QFP (Quad Flat Package)

DIP(Dual In-Line Package)

Others

Technology Trends and Forecasts by Application [\$M shipment analysis from 2018 t%li%2030]:

Consumer Electronics

SOP (Small Outline Package)

GA (Grid Array)

QFP (Quad Flat Package)

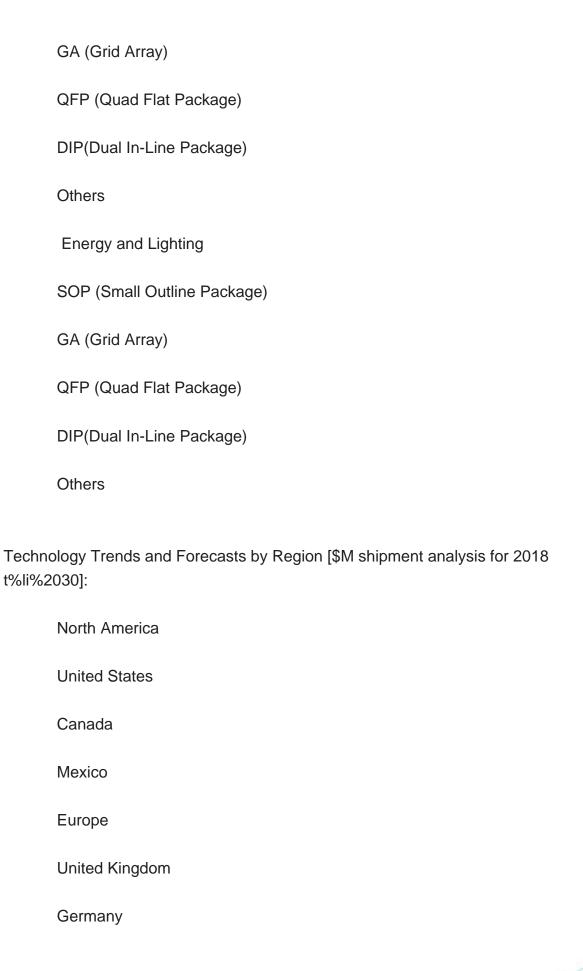
DIP(Dual In-Line Package)

Others



Aerospace and Defense SOP (Small Outline Package) GA (Grid Array) QFP (Quad Flat Package) DIP(Dual In-Line Package) Others **Medical Devices** SOP (Small Outline Package) GA (Grid Array) QFP (Quad Flat Package) DIP(Dual In-Line Package) Others Communications and Telecom SOP (Small Outline Package) GA (Grid Array) QFP (Quad Flat Package) DIP(Dual In-Line Package) Others Automotive Industry SOP (Small Outline Package)











Q.5 What are the business risks and threats t%li%these technologies in semiconductor and IC packaging material market?

Q.6 What are the latest developments in semiconductor and IC packaging material technologies? Which companies are leading these developments?

Q.7 Which technologies have potential of disruption in this market?

Q.8 Wh%li%are the major players in this semiconductor and IC packaging material market? What strategic initiatives are being implemented by key players for business growth?

Q.9 What are strategic growth opportunities in this semiconductor and IC packaging material technology space?



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